



Material Content Data Sheet



Sales Product Name		IPD90P04P4-05		Issued		3. October 2018		
MA#		MA003674388						
Package		PG-TO252-3-313		Weight*		319.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.26	1.26	12603	12603
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		461	
	non noble metal	copper	7440-50-8	147.096	46.01	46.07	460189	460788
	non noble metal	aluminium	7429-90-5	4.307	1.35	1.35	13476	13476
wire	non noble metal	aluminium	7429-90-5	4.307	1.35	1.35	13476	13476
encapsulation	organic material	carbon black	1333-86-4	1.364	0.43		4268	
	plastics	epoxy resin	-	23.874	7.47		74689	
	inorganic material	silicondioxide	60676-86-0	111.185	34.78	42.68	347840	426797
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11701	11701
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4444	4455
solder	non noble metal	tin	7440-31-5	0.065	0.02		202	
	noble metal	silver	7440-22-4	0.081	0.03		253	
	non noble metal	lead	7439-92-1	3.085	0.97	1.02	9651	10106
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59996	60074
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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